

Revisions

Rev. 0.0 : Development version

Rev. A.0 : Initial Release

- Change L1 to DR74-2R2-R
- Change U3 to W25Q16DWSSIG (SOIC8 208mil)

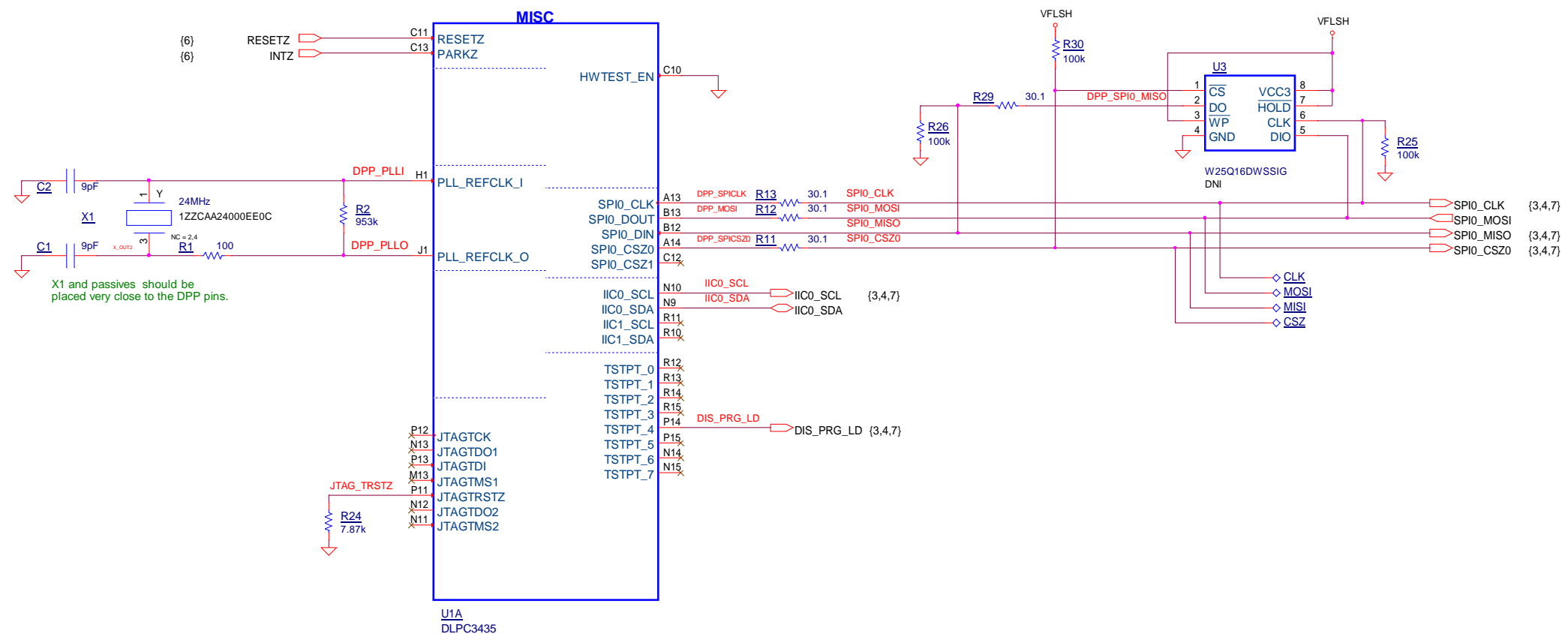
Rev. B.0 : minor BOM change

- Do not install TPGND3

ESD 2513848
PCB 2513849
CCA 2513850

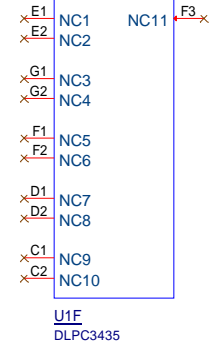
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| SYS | Dan Morgan | --- | TITLE TIDA-00325 DLP Display LightCrafter 2010 Formatter Board | | |
| APVD | Jeff Dennis | --- | DRAWING NO | 2513848 | REV B.0 |
| QA | --- | --- | 11 x 17 | Orcad Capture 16.2 | SHEET 1 of 7 |

DLPC3435 Clock, Reset, SPI and Flash Memory

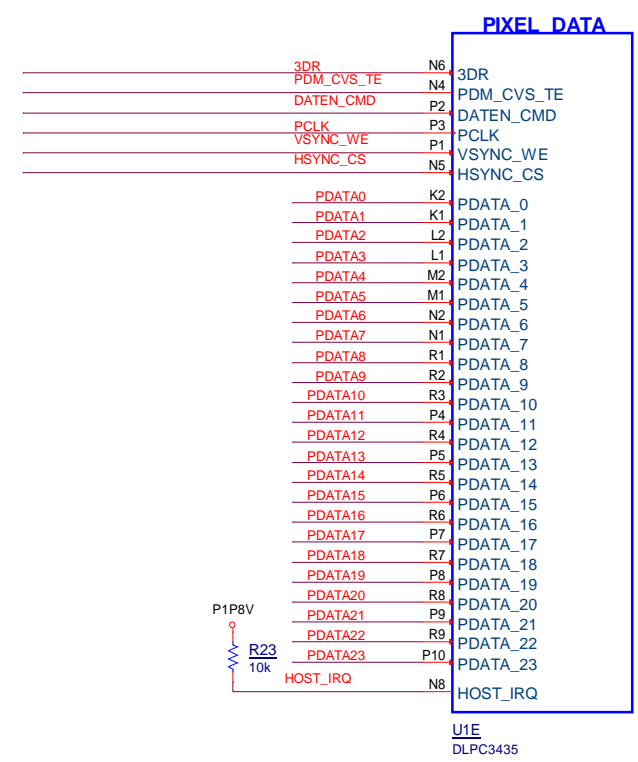
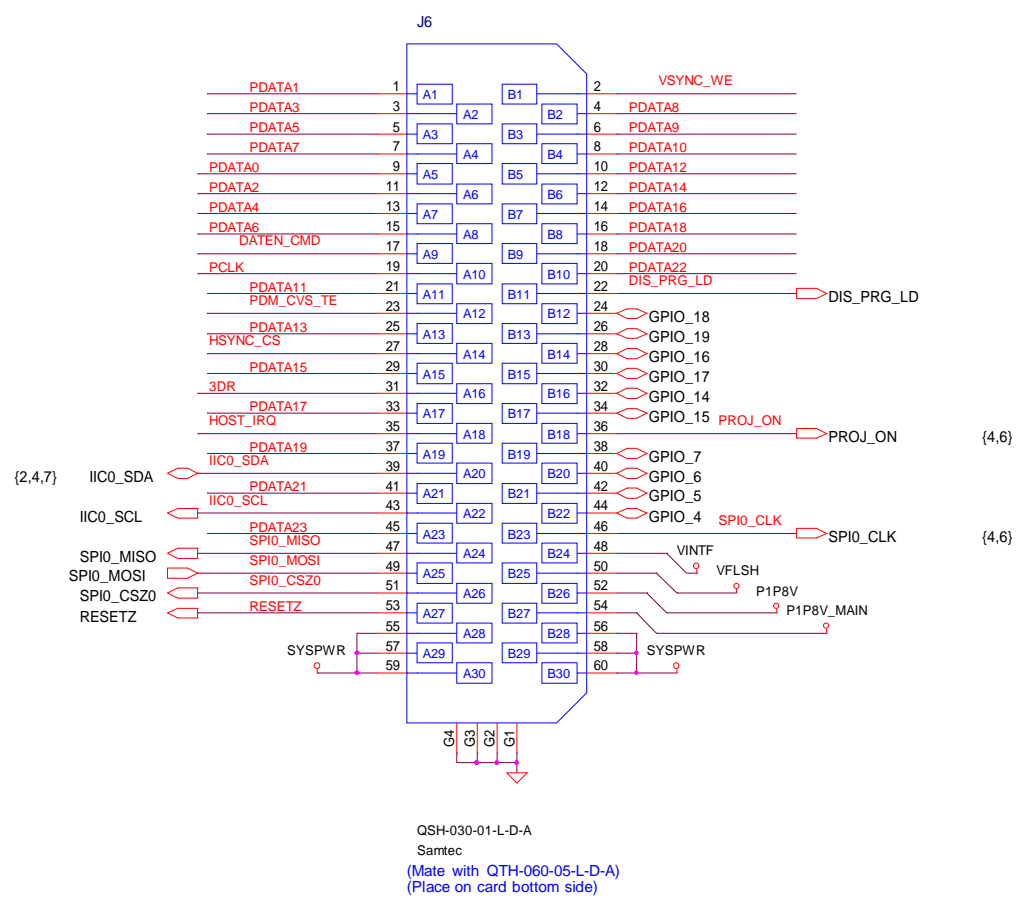


X1 and passives should be placed very close to the DPP pins.

NO CONNECT

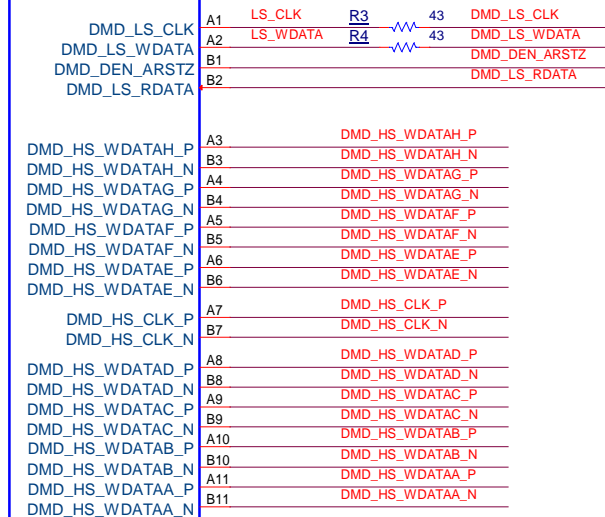


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| APVD | Jeff Dennis | --- | --- | DRAWING NO | 2513848 |
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| 11 x 17 | | | Orcad Capture 16.2 | SHEET 2 of 7 | |

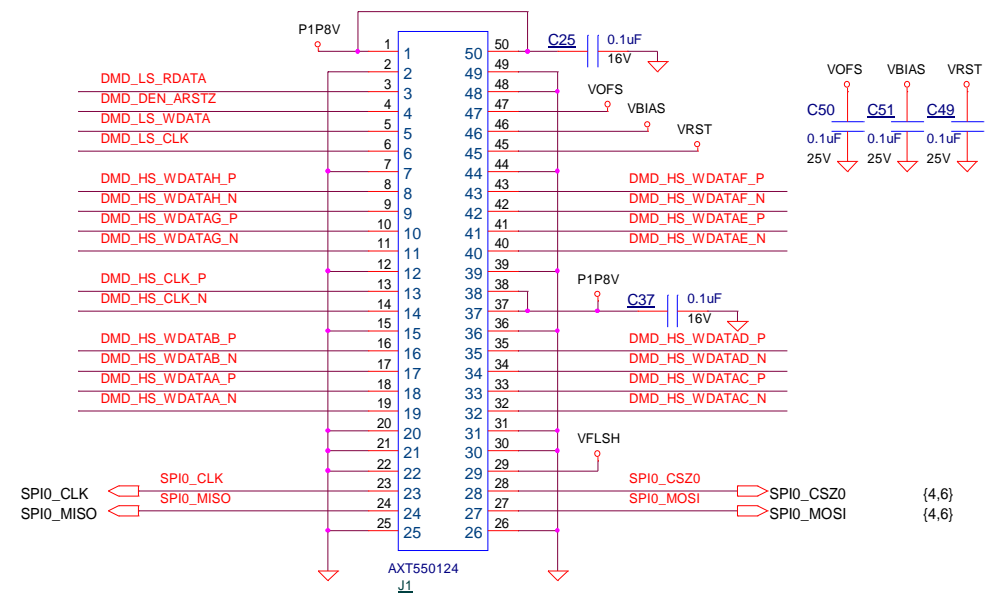


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| SYS | Dan Morgan | --- | --- | TITLE Front End Connections | |
| APVD | Jeff Dennis | --- | --- | DRAWING NO | 2513848 |
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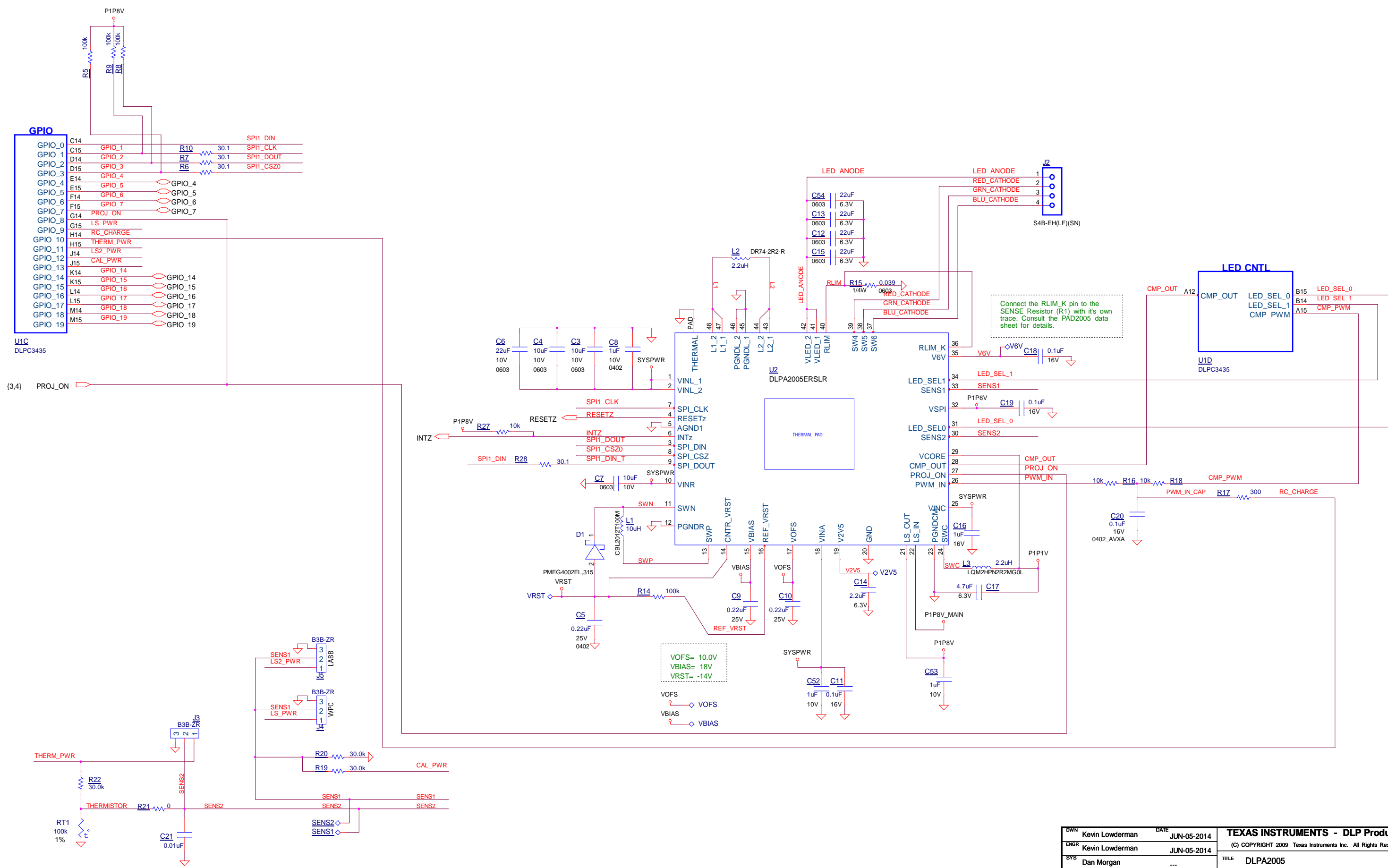
DMD INTERFACE



U1B
DLPC3435



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GPIO

| | | | | | |
|---------|-----|-----------|-----|------|-----------|
| GPIO_0 | C14 | GPIO_1 | R10 | 30.1 | SPI1_DIN |
| GPIO_1 | C15 | GPIO_2 | R7 | 30.1 | SPI1_CLK |
| GPIO_2 | D14 | GPIO_3 | R6 | 30.1 | SPI1_DOUT |
| GPIO_3 | D15 | GPIO_4 | | | SPI1_CSZ0 |
| GPIO_4 | E14 | GPIO_5 | | | GPIO_4 |
| GPIO_5 | E15 | GPIO_6 | | | GPIO_5 |
| GPIO_6 | F14 | GPIO_7 | | | GPIO_6 |
| GPIO_7 | F15 | GPIO_8 | | | GPIO_7 |
| GPIO_8 | G14 | PROJ_ON | | | GPIO_8 |
| GPIO_9 | G15 | LS_PWR | | | |
| GPIO_10 | H14 | RC_CHARGE | | | |
| GPIO_11 | H15 | THERM_PWR | | | |
| GPIO_12 | J14 | LS2_PWR | | | |
| GPIO_13 | J15 | CAL_PWR | | | |
| GPIO_14 | K14 | GPIO_14 | | | GPIO_14 |
| GPIO_15 | K15 | GPIO_15 | | | GPIO_15 |
| GPIO_16 | L14 | GPIO_16 | | | GPIO_16 |
| GPIO_17 | L15 | GPIO_17 | | | GPIO_17 |
| GPIO_18 | M14 | GPIO_18 | | | GPIO_18 |
| GPIO_19 | M15 | GPIO_19 | | | GPIO_19 |

U1C
DLPC3435

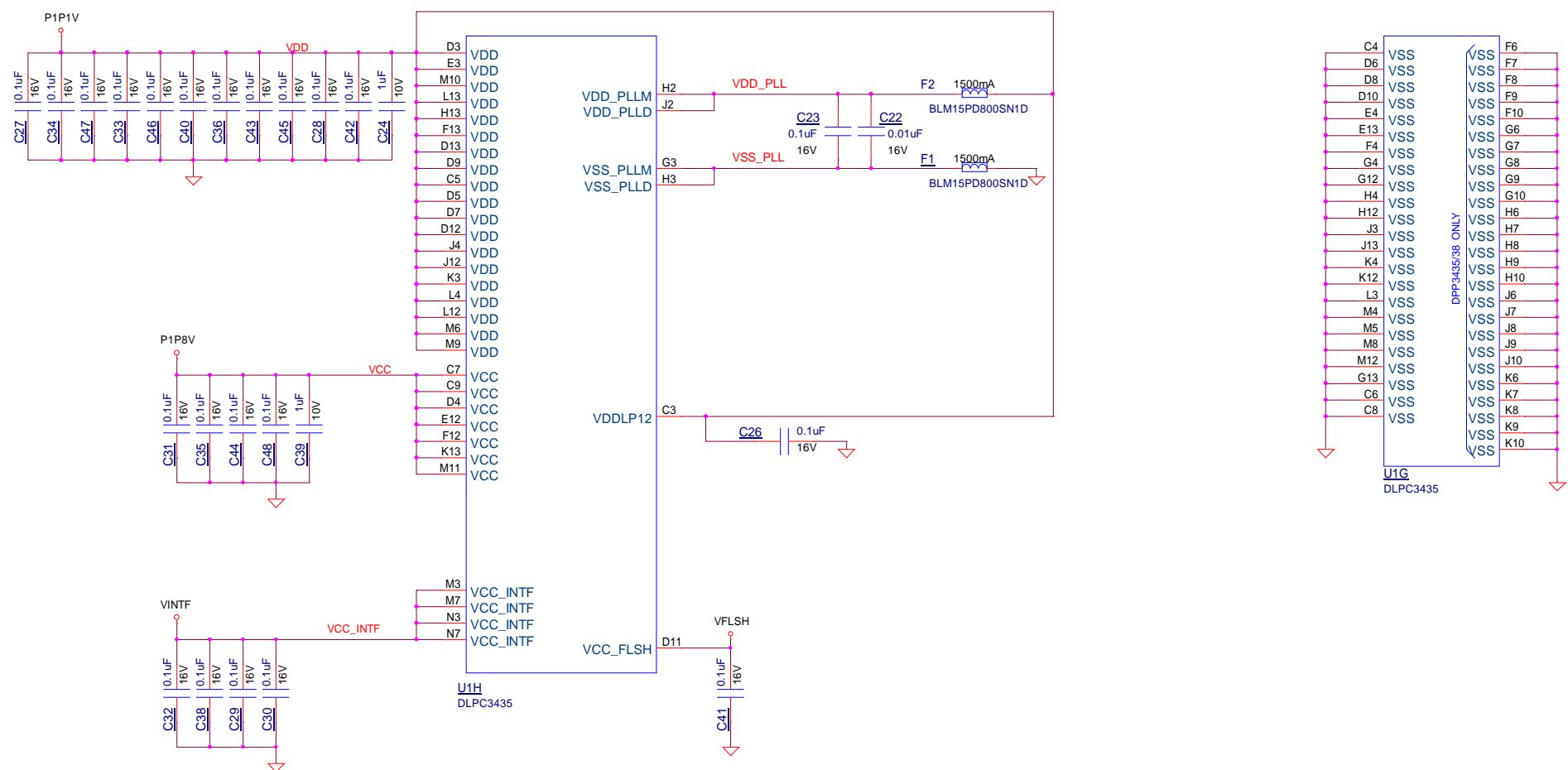
LED_CNTL

U1D
DLPC3435

VOFS= 10.0V
VBIAS= 18V
VRST= -14V

VOFS
VBIAS

| | | | | | |
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| SYS | Dan Morgan | | --- | TITLE | DLPA2005 |
| APVD | Jeff Dennis | | --- | DRAWING NO | 2513848 |
| QA | --- | | --- | REV | B.0 |



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| SYS | Dan Morgan | --- | --- | TITLE DLPC3435 Power | |
| APVD | Jeff Dennis | --- | --- | DRAWING NO | 2513848 |
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| | | | 11 x 17 | Orcad Capture 16.2 | SHEET 6 of 7 |

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